

10-31-2002

10/10/02



FORM PTO-1595

REC

U.S. DEPARTMENT OF COMMERCE

1/31/92

102266493  
PATENTS ONLY

Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please Record the attached original documents or copy thereof.

## 1. Name of conveying party(ies):

TAKESHI NOGAMI  
NAOKI KOMAI  
HIDEYUKI KITO  
MITSURU TAGUCHI

Additional name(s) of conveying party(ies) attached?

☐ Yes ☒ No

## 2. Name and address of receiving party(ies):

Name: Sony Corporation

Internal Address: \_\_\_\_\_

7-35, Kitashinagawa 6-chome

Shinagawa-ku, Tokyo 141, Japan

Street Address: \_\_\_\_\_

City: \_\_\_\_\_ State: \_\_\_\_\_ Zip: \_\_\_\_\_

Additional Name(s) & Address(es) attached ☐ Yes ☒ No

## 3. Nature of conveyance:

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other \_\_\_\_\_

Execution Date September 16, 17 & 20, 2002

## 4. Application (number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

## A. Patent Application No.(s)

U.S. Serial No. 10/149,481 filed June 11, 2002

Attorney Docket No. 09792909-5218

## B: Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

SONNENSCHN NATH & ROSENTHAL  
P.O. Box #061080  
Wacker Drive Station  
Sears Tower  
Chicago, IL 60606-1080  
Customer ID No. 26263

## 6. Total number of applications and patents involved

7. Total Fee (37 CFR 3.41) ..... \$ 40.00

☒ Enclosed

☐ Authorized to be charged to American Express  
Acct. No. 378571697401002. Form 2038 is attached for that purpose.

☒ Any deficiency is authorized to be charged to deposit account or any additional fees

## 8. Deposit Account Number:

19.3140

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

## 9. Statement and signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

David R. Metzger

Name of Person Signing

Signature

October 3, 2002

Date

Total number of pages 5

Mail documents to be recorded and required cover sheet information to:  
Commissioner of Patents and Trademarks  
Box Assignments  
Washington, D.C. 20231+

10/30/2002 DBYRNE 00000250 10149481

01 FC:8021

40.00 OP

PATENT  
REEL: 13425 FRAME: 0882

ASSIGNMENT

201P1506080

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in  
**SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF**

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Serial No. PCT/JP01/08989  
International Filing Date: October 12, 2001

This assignment executed on the dates indicated below.

TAKESHI NOGAMI  
Name of first or sole inventor

Execution date of U.S. Patent Application

KANAGAWA, JAPAN  
Residence of first or sole inventor

Takeshi Nogami  
Signature of first or sole inventor

Sept. 16 '02

Date of this assignment

NAOKI KOMAI

Name of second inventor

Execution date of U.S. Patent Application

KANAGAWA, JAPAN

Residence of second inventor

Signature of second inventor

Date of this assignment

HIDEYUKI KITO

Name of third inventor

Execution date of U.S. Patent Application

KANAGAWA, JAPAN

Residence of third inventor

Signature of third inventor

Date of this assignment

MITSURU TAGUCHI

Name of fourth inventor

Execution date of U.S. Patent Application

TOKYO, JAPAN

Residence of fourth inventor

Signature of fourth inventor

Date of this assignment

Name of fifth inventor

Execution date of U.S. Patent Application

Residence of fifth inventor

Signature of fifth inventor

Date of this assignment

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in  
**SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF**

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Serial No. PCT/JP01/08989

International Filing Date: October 12, 2001

This assignment executed on the dates indicated below.

TAKESHI NOGAMI  
Name of first or sole inventor

Execution date of U.S. Patent Application

KANAGAWA, JAPAN  
Residence of first or sole inventor

Signature of first or sole inventor

Date of this assignment

NAOKI KOMAI  
Name of second inventor  
KANAGAWA, JAPAN  
Residence of second inventor  
Naoki Komai  
September 17, 2002  
Signature of second inventor  
Date of this assignment

HIDEYUKI KITO  
Name of third inventor  
KANAGAWA, JAPAN  
Residence of third inventor  
Hideyuki Kito  
September 17, 2002  
Signature of third inventor  
Date of this assignment

MITSURU TAGUCHI  
Name of fourth inventor  
TOKYO, JAPAN  
Residence of fourth inventor  
Mitsuru Taguchi  
September 20, 2002  
Signature of fourth inventor  
Date of this assignment

Name of fifth inventor  
Execution date of U.S. Patent Application  
Residence of fifth inventor  
Signature of fifth inventor  
Date of this assignment